



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4964-6M		<b>Issued</b>		28. August 2013			
<b>MA#</b>		MA001069856							
<b>Package</b>		PG-SOT23-3-15		<b>Weight*</b>		9.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35596	35596	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73		
		non noble metal	titanium	7440-32-6	0.004	0.04		367	
		non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	noble metal	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365605	367146
		noble metal	gold	7440-57-5	0.018	0.18	0.18	1848	1848
		organic material	carbon black	1333-86-4	0.054	0.55		5463	
encapsulation	plastics	epoxy resin	-	1.153	11.75		117460		
		inorganic material	silicondioxide	60676-86-0	4.157	42.34	54.64	423401	546324
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15241	15241	
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15133	15133	
glue	plastics	epoxy resin	-	0.032	0.33		3275		
		noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18712
*deviation	< 10%		Sum in total:			100,00		1000000	

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com